REVISIONS APPROVED DATE DESCRIPTION LTR Change  $I_{\mbox{CEX}}$  maximum limits. 27 Mar 1986 Change  $I_{IL}$  maximum limits. Delete minimum limits from  $I_{II}$ . Editorial changes throughout. Selected item drawing Prepared in accordance with DOD-STD-100 REV PAGE REV STATUS REV Α PAGES OF PAGES DEFENSE ELECTRONICS SUPPLY CENTER Original date of drawing 19 Jan. 81 DAYTON, ONIC TITLE MICROCIRCUITS, DIGITAL, LOW POWER SCHOTTKY TTL, REGISTER FILE, MONOLITHIC SILICON CODE IDENT. NO. DWG NO. SIZE PAGE OF 10 REV 5962-E031 DESC FORM 144 AMSC N/A DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

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- 1.1 <u>Scope</u>. This drawing describes the requirements for monolithic silicon, low-power Schottky TTL, register file microcircuits. This drawing provides for a level of microcircuit quality and reliability assurance for acquisition of microcircuits in accordance with MIL-M-38510.
  - 1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit
01	54LS170	4 x 4 Register file with open collector outputs

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline				
E	D-2 (16-lead, 1/4" x 7/8"), dual-in-line package F-5 (16-lead, 1/4" x 3/8"), flat package				

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

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2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

**STANDARD** 

MILITARY

MIL-STD-883

- Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein. The country of manufacture requirement of MIL-M-38510 does not apply.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
- 3.2.1 <u>Design documentation</u>. The design documentation shall be in accordance with MIL-M-38510 and, unless otherwise specified in the contract or purchase order, shall be retained by the manufacturer but be available for review by the acquiring activity or contractor upon request.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.3 Truth tables. The truth tables shall be as specified on figure 2.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2.
  - 3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510.
- 3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.5 Marking. Marking shall be in accordance with MIL-M-38510 except the part number shall be in accordance with 1.2 herein. The Yendor Similar Part Number may also be marked in accordance with 6.8 herein. Both part numbers, when used, shall be printed on the same surface. The "M38510/XXXYY" part number and the "JAN" or "J" mark shall not be used. Lead finish letter "X" is used only as specified in MIL-M-38510 and shall not be marked on the microcircuit or its packaging. The country of origin shall be marked on the microcircuit.
- 3.6 Quality assurance requirements. Microcircuits furnished under this drawing shall have been subjected to, and passed all the requirements, tests, and inspections detailed herein including screening and quality conformance.

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TI	ABLE I.	Electrical performance character	istics.			
	<del></del>	Conditions	T	Lim	its	
Test	Symbol	-55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A  subgroups 	l Min	l l Max l	Unit   
Collector cutoff current	ICEX		1, 2, 3	   	   100   	Ι Ι μ <b>Α</b> Ι
Low level output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V I <sub>OL</sub> = 4 mA	1, 2, 3	 	   0.4 	<b>V</b>
Input clamp voltage	V <sub>IC</sub>	V <sub>CC</sub> = 4.5 V I <sub>IN</sub> = -18 mA   T <sub>C</sub> = +25°C	1		  -1.5 	   V 
High-level input current, all inputs except GR and	I <sub>IH1</sub>	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 2.7 V	1, 2, 3	   	20	   μ <b>Α</b> 
	I <sub>IH2</sub>	T 	1, 2, 3	l     	40	μ <b>Α</b>
High level input current, all inputs except GR and	I IH3	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 5.5 V	1, 2, 3	       •	100	   μΑ 
	I IH4	T ! !	1, 2, 3	!   	200	μ <b>Α</b>
Low level input current at data, read select, and write select	IIIL1	Y <sub>CC</sub> = 5.5 V Y <sub>IN</sub> = 0.4 V	1, 2, 3	! ! !	4	mA   mA   
Low level input current at read enable	I <sub>IL2</sub>	† ! ! !	1, 2, 3		  8 	l mA
Low-level input current at write enable	I <sub>IL3</sub>	†     	1, 2, 3	     	  8 	mA 
Supply current	ICC	V <sub>CC</sub> = 5.5 V	1, 2, 3	 	   40 	   mA 

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	T	Conditions   -55°C < T <sub>C</sub> < +125°C		Lim	its	<u> </u>
Test	Symbol	-55°C < T <sub>C</sub> < +125°C   unless otherwise specified 	Group A	Min	   Max	T Unit   
Propagation delay	i  t <sub>PLH1</sub>	V <sub>CC</sub> = 5.0 V  C <sub>L</sub> = 50 pF ±10%  R <sub>L</sub> = 2 kΩ ±5% 	9, 10, 11		65	l ns
	  t <sub>PHL1</sub>		9, 10, 11		52	l ns
Propagation delay time, from read	  tpLH2		9, 10, 11		   58 	ns
select	tpHL2	  -	9, 10, 11		   58 	l ns
Propagation delay time, from write	tpLH3	T   	9, 10, 11		65	ns
enable	tpHL3	T   	9, 10, 11	<u> </u>	   58 	ns
Propagation delay time, from read	t <sub>PLH4</sub>	]   	9, 10, 11	<b> </b> 	   46 	l ns
enable	tpHL4		9, 10, 11		46	ns

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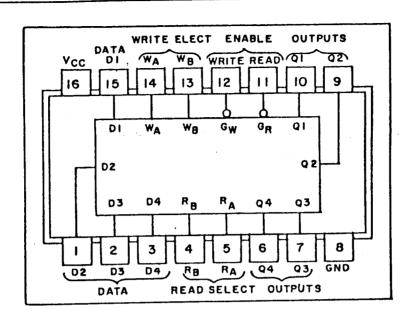


FIGURE 1. Terminal connections.

Write function table (see notes A, B, and C)

Read function table (see notes A and D)

Wr	ite i	nputs	T	W	ord	
WВ	WA	GW	Q	1	2	3
L H H X	H H X	L L L H	Q = D Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q	Q = D Q0 Q0 Q0 Q0	Q <sub>0</sub> Q <sub>0</sub> Q <sub>0</sub> Q <sub>0</sub>	Q0 Q0 Q0 Q = D Q0

Read inputs			Outputs				
R <sub>B</sub>	RA	GR	Q1	Q2	Q3	Q4	
L   L   H   H	L H L H	L L L H	WOB1   W1B1   W2B1   W3B1   H	WOB2 W1B2 W2B2 W3B2 H	WOB3 W1B3 W2B3 W3B3 H	WOB4 W1B4 W2B4 W3B4 H	

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A.  $H = high\ level$ ,  $L = low\ level$ , X = irrelevant,  $Z = high\ impedance\ (off)$ B. (Q = D) - The four selected internal flip-flop outputs will assume the states applied to the four external data inputs.

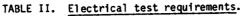
C.  $Q_0$  = the level of Q before the indicated input conditions were established. D. WOB1 = The first bit of word 0, etc.

FIGURE 2. Truth tables

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16: C 1CM 1446		$\blacksquare$				

- 3.6.1 Screening. Screening shall be in accordance with method 5004, class B, of MIL-STD-883 and 4.2 herein.
- 3.6.2 Qualification. Qualification inspection for the device type specified herein shall not be required.
- 3.6.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and 4.4 herein.
- 3.7 Manufacturer eligibility. To be eligible to supply microcircuits to this drawing, a manufacturer shall have manufacturer certification in accordance with MIL-M-38510 for at least one line and have part I listing on Qualified Products List QPL-38510 for at least one device type (not necessarily the one for which the acquisition of this drawing is to apply).
- 3.8 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply (see 6.7 and 6.8).
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein.
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test (method 1015 of MIL-STD-883).
    - (1) Test condition A, B, C, or D.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
  - c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.
- 4.3 Qualification inspection. Qualification inspection for the device type specified herein shall not be  $\frac{1}{required}$ .
- 4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883. Groups A and B inspections shall be performed on each inspection lot or as specified in method 5005, of MIL-STD-883. Groups C and D shall be performed on a periodic basis in accordance with MIL-M-38510. Generic test data (see 6.5) may be used to satisfy the requirements for groups C and D inspections. Manufacturers shall keep lot records for 5 years (minimum), monitor for compliance to the prescribed procedures, and observe that satisfactory manufacturing conditions and records on lots are maintained for these devices. The records, including an attributes summary of all screening and quality conformance inspections conducted on each lot, shall be available for review by customers at all times.

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   MIL-STD-883 test requirements 	Subgroups (per method 5005, table I)
Interim electrical parameters   (method 5004) 	
Final electrical test parameters  (method 5004)	1*, 2, 3, 9
IGroup A test requirements  (method 5005)	1, 2, 3, 7, 9
Groups C and D end-point  electrical parameters  (method 5005)	1, 2, 3   
Additional electrical subgroups lfor group C periodic inspections	10, 11**   

- PDA applies to subgroup 1 (see 4.2c).
   Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.
- 4.4.1 Group A inspection. Group A inspection shall consist of the test subgroups and LTPD values shown in table I of method 5005 of MIL-STD-883, class B, and as follows:
  - a. Tests shall be as specified in table II herein.
  - b. Subgroups 4, 5, 6, and 8 of table I of method 5005 of MIL-STD-883 shall be omitted.
  - c. Subgroup 7 tests shall verify the truth table.
- 4.4.2 Group B inspection. Group B inspection shall consist of the test subgroups and LTPD values shown in table IIb of method 5005 of MIL-STD-883, class B.
- 4.4.3 Groups C and D inspections. Groups C and D inspections shall consist of the test subgroups and LTPD values shown in tables III and IV of method 5005 of MIL-STD-883, class B, and as follows:
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
    - (1) Test condition A, B, C, or D.
    - (2)  $T_A = +125$ °C, minimum.
    - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Notes. Only the note "Reevaluation of lot quality" of the notes specified in MIL-M-38510 shall apply to this drawing.
- 6.2 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. This drawing is intended exclusively to prevent the proliferation of unnecessary duplicate specifications, drawings, and stock catalog listings. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, this drawing will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
  - 6.3 Ordering data. The contract or purchase order should specify the following:
    - a. Complete part number (see 1.2).
    - b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
    - c. Requirements for certificate of compliance, if applicable.
    - Requirements for notification of change of product or process to contracting activity, if applicable.
    - Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements will not apply to direct shipment to the Government.
  - 6.4 Replaceability. Replaceability is determined as follows:
    - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
    - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31902B---
- 6.5 Generic test data. Generic test data may be used to satisfy the requirements of 4.4.3. Group C generic test data shall be on date codes no more than 1 year old and on a die in the same microcircuit group (see appendix E of MIL-M-38510) with the same material, design and process and from the same plant as the die represented. Group D generic data shall be on date codes no more than 1 year old and on the same package type (terms, definitions, and symbols of MIL-M-38510) and from the same plant as the package represented. The vendor is required to retain the generic data for a period of not less than 5 years from the date of shipment.
- 6.6 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, OH 45444, or telephone 513-296-5375.
- Submission of certificate of compliance. The certificate of compliance submitted to DESC-ECS, prior to listing as an approved source of supply in 6.8, shall state the manufacturer's product meets the requirements herein.

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6.8 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.8) has been submitted to DESC-ECS.

DESC drawing part number	Vendor   FSCM   number	Vendor   similar part   number 	Replacement  military specification    part number
8002501EX	04713 01295 07263	54LS170/BEBJC   SNJ54LS170J   54LS170DMQB	M38510/31902BEX
8002501FX	04713 01295 07263	54LS170/BFBJC   SNJ54LS170W   54LS170FMQB	M38510/31902BFX

Vendor FSCM number	Vendor name and address		
07263	Fairchild Semiconductor 333 Western Avenue South Portland, ME 04106		
04713	Motorola, Inc. 7402 South Price Road Tempe, AZ 85283		
01295	Texas Instruments, Inc. P.O. Box 6448 Midland, TX 79701		

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